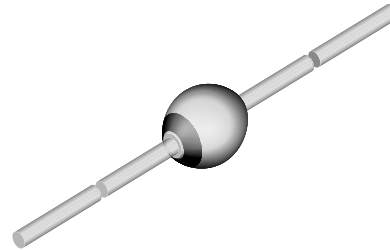


Ultra Fast Avalanche Sinterglass Diode

Features

- Glass passivated junction
- Hermetically sealed package
- Very low switching losses
- Low reverse current
- High reverse voltage
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



949539

Applications

Switched mode power supplies
High-frequency inverter circuits

Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: approx. 369 mg

Mechanical Data

Case: SOD-57 Sintered glass case

Parts Table

Part	Type differentiation	Package
BYV26A	$V_R = 200\text{ V}$; $I_{FAV} = 1\text{ A}$	SOD-57
BYV26B	$V_R = 400\text{ V}$; $I_{FAV} = 1\text{ A}$	SOD-57
BYV26C	$V_R = 600\text{ V}$; $I_{FAV} = 1\text{ A}$	SOD-57
BYV26D	$V_R = 800\text{ V}$; $I_{FAV} = 1\text{ A}$	SOD-57
BYV26E	$V_R = 1000\text{ V}$; $I_{FAV} = 1\text{ A}$	SOD-57

Absolute Maximum Ratings

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Part	Symbol	Value	Unit
Reverse voltage = Repetitive peak reverse voltage	see electrical characteristics	BYV26A	$V_R = V_{RRM}$	200	V
		BYV26B	$V_R = V_{RRM}$	400	V
		BYV26C	$V_R = V_{RRM}$	600	V
		BYV26D	$V_R = V_{RRM}$	800	V
		BYV26E	$V_R = V_{RRM}$	1000	V
Peak forward surge current	$t_p = 10\text{ ms}$, half sinewave		I_{FSM}	30	A
Average forward current			I_{FAV}	1	A
Non repetitive reverse avalanche energy	$I_{(BR)R} = 1\text{ A}$, inductive load		E_R	10	mJ
Junction and storage temperature range			$T_J = T_{stg}$	- 55 to + 175	$^{\circ}\text{C}$

Maximum Thermal Resistance

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Symbol	Value	Unit
Junction ambient	$l = 10\text{ mm}$, $T_L = \text{constant}$	R_{thJA}	45	K/W

Electrical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
Forward voltage	$I_F = 1\text{ A}$		V_F			2.5	V
	$I_F = 1\text{ A}$, $T_J = 175\text{ }^{\circ}\text{C}$		V_F			1.3	V
Reverse current	$V_R = V_{RRM}$		I_R			5	μA
	$V_R = V_{RRM}$, $T_J = 150\text{ }^{\circ}\text{C}$		I_R			100	μA
Reverse breakdown voltage	$I_R = 100\text{ }\mu\text{A}$	BYV26A	$V_{(BR)R}$	300			V
		BYV26B	$V_{(BR)R}$	500			V
		BYV26C	$V_{(BR)R}$	700			V
		BYV26D	$V_{(BR)R}$	900			V
		BYV26E	$V_{(BR)R}$	1100			V
Reverse recovery time	$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $i_R = 0.25\text{ A}$	BYV26A-BYV26C	t_{rr}			30	ns
		BYV26D-BYV26E	t_{rr}			75	ns

Typical Characteristics ($T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

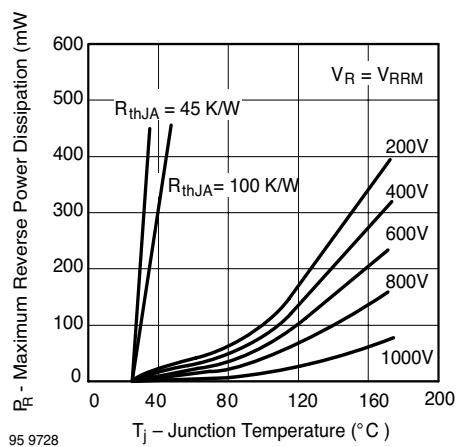


Figure 1. Max. Reverse Power Dissipation vs. Junction Temperature

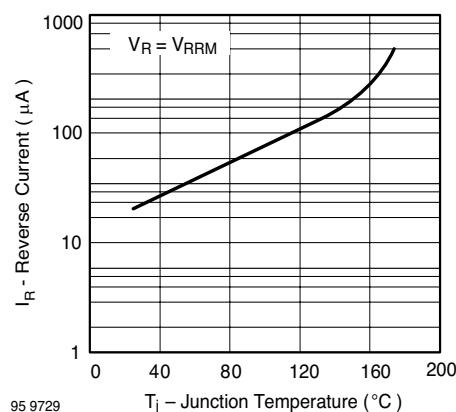


Figure 2. Max. Reverse Current vs. Junction Temperature